

Rev. V3

Features

Low Conversion Loss: 7.5 dB
High Linearity: 22 dBm IIP3
High Image Rejection: 22 dBc
Wide IF Bandwidth: DC to 3.5 GHz

High Isolation

• Die Size: 1.85 × 2.00 × 0.10 mm

RoHS* Compliant

Applications

 Test & Measurement, Microwave Radio, and Radar

Description

MAMX-011044-DIE is an image-reject passive diode mixer MMIC. The mixer offers low conversion loss, high linearity and a wide IF bandwidth. The image-reject circuit configuration provides excellent port isolation while internal 50-ohm matching simplifies its application.

This mixer is well suited for applications such as test and measurement, microwave radio and radar.

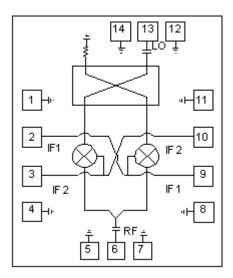
MAMX-011044-DIE is also available in a 4 mm QFN package. Refer to datasheet MAMX-011044.

Ordering Information

Part Number	Package
MAMX-011044-DIE	Vacuum Release Gel Pack ¹
MAMX-011044-SB2	Sample Board

1. Die quantity varies.

Functional Schematic



Bond-pad Configuration

Pin #	Function		
1, 4, 5, 7, 8, 11, 12, 14	Ground ²		
2	IF1 (I) ³		
3	IF2 (Q) ³		
6	RF		
9	IF1 (I) ³		
10	IF2 (Q) ³		
13	LO		
15	Ground ⁴		

- 2. These pads are internally connected to ground, and they can be left unconnected.
- Only one side IF1 and IF2 need to be connected, and leave the other side IF1 and IF2 unconnected.
- The backside of the die must be connected to RF, DC and thermal ground.

^{*} Restrictions on Hazardous Substances, compliant to current RoHS EU directive.



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Electrical Specifications⁵: $F_{IF} = 500$ MHz, $P_{LO} = 18$ dBm, $T_A = 25$ °C, $Z_0 = 50$ Ω

Parameter	Test Conditions	Units	Min.	Тур.	Max.
LO and RF Frequency	_	GHz	2.5	_	9
IF Frequency	_	GHz	0	_	3.5
LO Power	_	dBm	_	18	_
Conversion Loss	2.5 - 5.0 GHz 5.0 - 7.0 GHz 7.0 - 9.0 GHz	dB	_	7.5 7.5 7.5	8.5 10.0 11.0
Input P1dB	_	dBm	_	13	
Input IP3	P _{RF} = -10 dBm/tone, Δf = 1 MHz	dBm	_	22	_
Input IP2 (Half IF)	P _{RF} = -10 dBm	dBm	_	58	_
LO-to-RF Isolation	_	dB	_	45	_
LO-to-IF Isolation	_	dB	_	45	
RF-to-IF Isolation	_	dB	_	15	
Image Rejection	_	dBc	_	20	1
Amplitude Imbalance	_	dB	_	±0.5	_
Phase Imbalance	_	۰	_	±5.0	_
RF Return Loss	RF = 3.5 GHz	dB	_	8	_
IF Return Loss	IF = 2 GHz	dB	_	13	_

^{5.} All specifications refer to down-conversion USB operation, unless otherwise noted.

Absolute Maximum Ratings^{6,7}

Parameter	Absolute Maximum		
LO Power	23 dBm		
RF or IF Power	20 dBm		
Junction Temperature ⁸	+150°C		
Operating Temperature	-55°C to +85°C		
Storage Temperature	-65°C to +150°C		

^{6.} Exceeding any one or combination of these limits may cause permanent damage to this device.

Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these HBM Class 1B devices.

MACOM does not recommend sustained operation near these survivability limits.

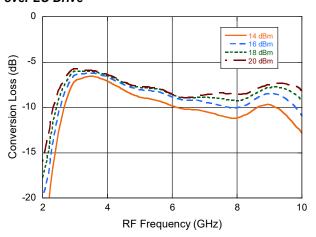
^{8.} Operating at nominal conditions with $T_J \le +150$ °C will ensure MTTF > 1 x 10^6 hours.



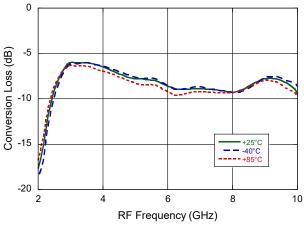
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Typical Performance Curves: 90° Hybrid @ 500 MHz IF

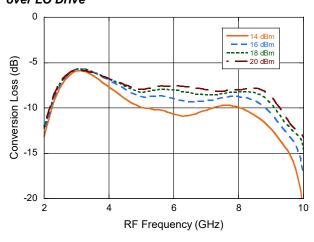
Down Conversion Gain (Upper Side Band) over LO Drive



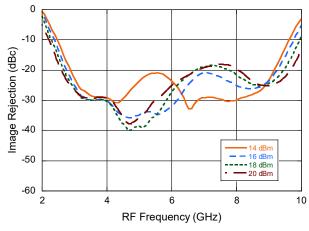
Down Conversion Gain (Upper Side Band) over Temperature



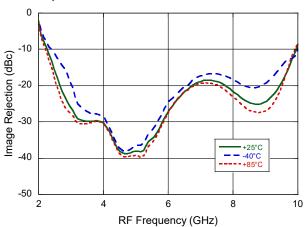
Down Conversion Gain (Lower Side Band) over LO Drive



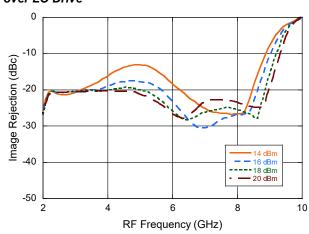
Down Conversion Image Rejection (Upper Side Band) over LO Drive



Down Conversion Image Rejection (Upper Side Band) over Temperature



Down Conversion Image Rejection (Lower Side Band) over LO Drive

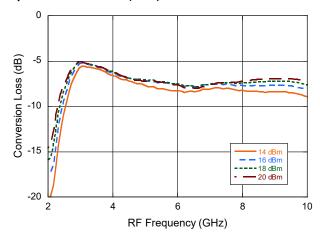




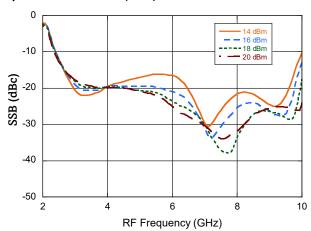
MAMX-011044-DIE Rev. V3

Typical Performance Curves: 90° Hybrid @ 500 MHz IF

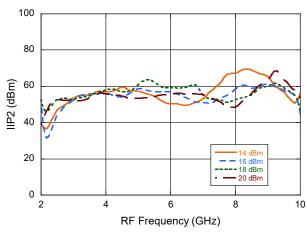
Up Conversion Gain (USB) over LO Drive



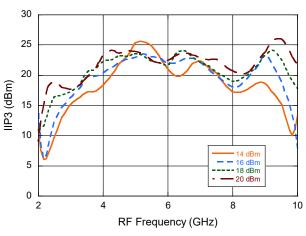
Up Conversion SSB (USB) over LO Drive



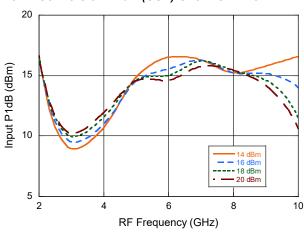
Down Conversion IIP2 (USB) over LO Drive



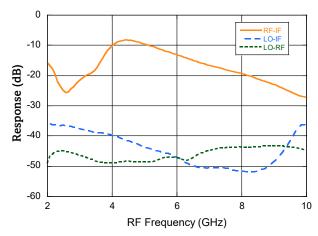
Down Conversion IIP3 (USB) over LO Drive



Down Conversion P1dB (USB) Over LO Drive



Down Conversion Isolation



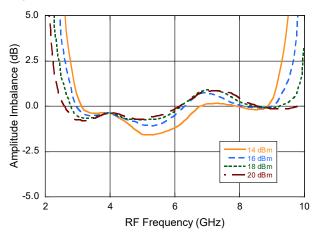
4



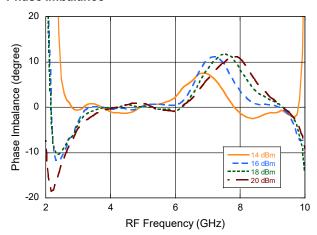
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Typical Performance Curves:

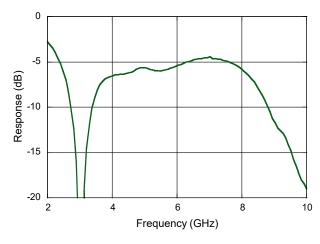
Amplitude Imbalance



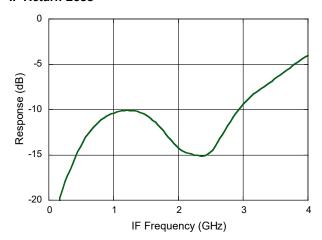
Phase Imbalance



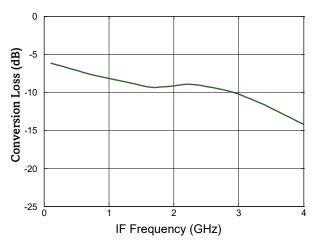
RF Return Loss



IF Return Loss



IF Bandwidth





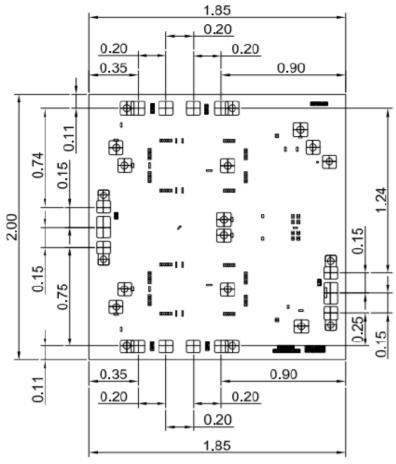
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MxN Spurious Rejection at IF Port (dBc IF)

RF = 5.5 GHz at -10 dBm LO = 5.0 GHz at +18 dBm

	NxLO					
MxRF	0	1	2	3	4	
0	X	8	20	8	15	
1	5	0	26	81	44	
2	X	98	75	82	95	
3	88	Х	90	75	90	
4	Х	100	X	102	106	

Outline Drawing



Notes:

Units are in microns with a tolerance of ±5 μm, except for die exterior dimensions which are street-center-to-street-center, nominal kerf, ±20 μm. Die thickness is 100 ±10 μm.

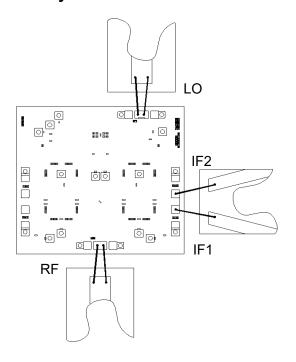
RF and LO bond-pads are $160 \times 100 \ \mu m$.

IF bond-pads are 100 × 100 μm.



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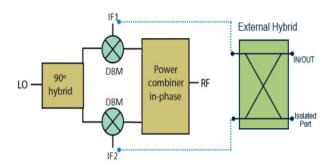
Assembly Guideline



Notes:

- Attach bare die to PCB or carrier using conductive epoxy. Bond die signal pads to PCB 50 Ω traces using 1.0 mil gold wire.
- Two bond wires are recommended on each signal pad for optimal performance. There is no need to bond the die ground pads.

Hybrid Configuration



External Hybrid

- Down conversion and Up conversion data captured with external hybrid 90° coupler part number: ATM PNR H912.
- RF Upper Side Band (USB) mode connect hybrid 0° port to IF1 mixer port, 90° hybrid port to IF2 mixer port.
- RF Lower Side Band (LSB) mode connect hybrid 0° port to IF2 mixer port, 90° hybrid port to IF1 mixer port.